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Lead-Free Solders Workshop 2006 - TMS Annual Meeting 2006, San Antonio, CA, March 12, 2006

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The Mutual Impact of Lead-free Soldering and Fluxing Technology	*N.-C. Lee*	View Presentation
Sn-Whiskers: Truths and Myths	*J. Osenbach*	View Presentation
Deformation and Microstructural Evolution Processes in Lead-Free Sn-Ag Solder Joints due to Creep, Aging and Thermomechanical Fatigue and Preliminary Results on SAC Ball Grid Arrays	*T. R. Bieler, E. J. Cotts, L. P. Lehman, A. Zamiri and F. Pourboghart*	View Presentation
Manufacturing and Reliability of SnAgCu: Issues of "Backward" and "Forward" Compatibility	*C. Handwerker, K. Moon, U. Kattner, B. Boettinger, and M. Williams*	View Presentation
What the Electronics Industry Missed for 80 Years … ... Interfacial Void Formation in Solder Joints with Cu Pad Structures during Thermal Aging	*D.W. Henderson, P. Borgesen, P. Kondos, I. De Sousa, L. Patry, and L. Yin*	View Presentation
Cross-Interaction between Cu and Ni in Lead-Free Solder Joints	*C.R. Kao*	View Presentation
Thermomechanical Fatigue and Fracture of Sn-based Solders	*K.N. Subramanian and A. Lee*	View Presentation
Panel Discussion Summary	*F. Hua*	View Presentation